

Preliminary datasheet

Short circuit rugged 750 V EDT2 IGBT in reflow-solderable package co-packed with soft and fast recovery diode

Features

- $V_{CE} = 750\text{ V}$
- $I_C = 200\text{ A}$
- Suitable for 470 V V_{DC} systems and increase overvoltage margin for 400 V V_{DC} systems
- Very low $V_{CEsat} = 1.4\text{ V}$ (typ.) at $I_{Cnom} = 200\text{ A}$, 25°C
- Short circuit robust $t_{sc} = 5\text{ }\mu\text{s}$ at $V_{CE} = 470\text{ V}$, $V_{GE} = 15\text{ V}$
- Up to 40% less System R_{th} due to reflow capability, increased power output
- Self limiting current under short circuit condition
- Positive thermal coefficient and very tight parameter distribution for easy paralleling
- A Reduced number of parallel devices is required due to $I_{nom} = 200\text{ A}$
- Excellent current sharing in parallel operation
- Smooth switching characteristics
- Low gate charge Q_G
- Simple gate drive design
- Co-packed with fast soft recovery emitter controlled 3 diode
- Low EMI signature
- TO247PLUS package with high creepage distance
- High reliability and operating lifetime
- Resistive weldable pins for direct busbar connections
- Drop-in replacement for $I_C = 200\text{ A}$, $T_c = 100^\circ\text{C}$ devices



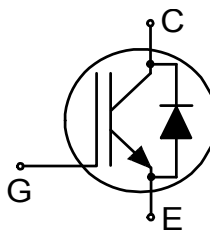
Potential applications

- xEV traction inverter
- DC-link discharge switch
- Automotive aux-drives

Product validation

- Qualified for automotive applications. Product Validation according to AEC-Q101
- Qualified Reflow device according to JEDEC J-STA-020 MSL2

Description



Type	Package	Marking
AIKQB200N75CP2	PG-TO247-3-PLUS-NN8.5	AKQB20FCP



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1 Package

1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in.) from case	L_E			13		nH
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	reflow soldering (MSL2 according to JEDEC J-STA-020)			260	°C
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W
IGBT thermal resistance, junction-case	$R_{th(j-c)}$			0.12	0.16	K/W
Diode thermal resistance, junction-case	$R_{th(j-c)}$			0.23	0.3	K/W

2 IGBT

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CE}	$T_{vj} \geq 25\text{ °C}$		750	V
DC collector current, limited by T_{vjmax}	I_C		$T_c = 25\text{ °C}$	250	A
			$T_c = 100\text{ °C}$	200	
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpulse}			600	A
Turn-off safe operating area		$V_{CE} \leq 750\text{ V}, T_{vj} \leq 175\text{ °C}$		600	A
Gate-emitter voltage	V_{GE}			± 20	V
Transient gate-emitter voltage	V_{GE}	$t_p = 10\text{ }\mu\text{s}, D < 0.01$		± 30	V
Short-circuit withstand time	t_{SC}	$V_{CC} \leq 470\text{ V}, V_{GE} = -8/15\text{ V}$, Allowed number of short circuits < 1000, Time between short circuits $\geq 1.0\text{ s}, T_{vj} = 25\text{ °C}$		5	μs
Power dissipation	P_{tot}	$T_{vj} = 175\text{ °C}$	$T_c = 25\text{ °C}$	938	W
			$T_c = 100\text{ °C}$	469	

Table 3 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	V_{CEsat}	$I_C = 200\text{ A}$, $V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$		1.4	1.65	V
			$T_{vj} = 175\text{ °C}$		1.7		
Gate-emitter threshold voltage	V_{GETh}	$I_C = 2.6\text{ mA}$, $V_{CE} = V_{GE}$		5	5.75	6.5	V
Zero gate-voltage collector current	I_{CES}	$V_{CE} = 750\text{ V}$, $V_{GE} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$			200	μA
			$T_{vj} = 175\text{ °C}$		5		mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$				100	nA
Transconductance	g_{fs}	$I_C = 200\text{ A}$, $V_{CE} = 20\text{ V}$			140		S
Short-circuit collector current	I_{SC}	$V_{CC} \leq 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $t_{SC} \leq 5\text{ }\mu\text{s}$, Allowed number of short circuits < 1000, Time between short circuits $\geq 1.0\text{ s}$, $T_{vj} = 25\text{ °C}$			1250		A
Input capacitance	C_{ies}	$V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 100\text{ kHz}$			21250		pF
Output capacitance	C_{oes}	$V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 100\text{ kHz}$			535		pF
Reverse transfer capacitance	C_{res}	$V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 100\text{ kHz}$			93		pF
Gate charge	Q_G	$V_{CC} = 600\text{ V}$, $I_C = 200\text{ A}$, $V_{GE} = -8/15\text{ V}$			1256		nC
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $R_{G(on)} = 5\text{ }\Omega$, $R_{G(off)} = 5\text{ }\Omega$	$T_{vj} = 25\text{ °C}$, $I_C = 200\text{ A}$		89		ns
			$T_{vj} = 175\text{ °C}$, $I_C = 200\text{ A}$		85		
Rise time (inductive load)	t_r	$V_{CC} = 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $R_{G(on)} = 5\text{ }\Omega$, $R_{G(off)} = 5\text{ }\Omega$	$T_{vj} = 25\text{ °C}$, $I_C = 200\text{ A}$		120		ns
			$T_{vj} = 175\text{ °C}$, $I_C = 200\text{ A}$		117		
Turn-off delay time	$t_{d(off)}$	$V_{CC} = 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $R_{G(on)} = 5\text{ }\Omega$, $R_{G(off)} = 5\text{ }\Omega$	$T_{vj} = 25\text{ °C}$, $I_C = 200\text{ A}$		266		ns
			$T_{vj} = 175\text{ °C}$, $I_C = 200\text{ A}$		284		
Fall time (inductive load)	t_f	$V_{CC} = 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $R_{G(on)} = 5\text{ }\Omega$, $R_{G(off)} = 5\text{ }\Omega$	$T_{vj} = 25\text{ °C}$, $I_C = 200\text{ A}$		46		ns
			$T_{vj} = 175\text{ °C}$, $I_C = 200\text{ A}$		60		
Turn-on energy ¹⁾	E_{on}	$V_{CC} = 470\text{ V}$, $V_{GE} = -8/15\text{ V}$, $R_{G(on)} = 5\text{ }\Omega$, $R_{G(off)} = 5\text{ }\Omega$	$T_{vj} = 25\text{ °C}$, $I_C = 200\text{ A}$		15.3		mJ
			$T_{vj} = 175\text{ °C}$, $I_C = 200\text{ A}$		16.3		

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-off energy	E_{off}	$V_{\text{CC}} = 470 \text{ V}$, $V_{\text{GE}} = -8/15 \text{ V}$, $R_{\text{G(on)}} = 5 \Omega$, $R_{\text{G(off)}} = 5 \Omega$	$T_{\text{vj}} = 25 \text{ }^{\circ}\text{C}$, $I_{\text{C}} = 200 \text{ A}$	7		mJ
			$T_{\text{vj}} = 175 \text{ }^{\circ}\text{C}$, $I_{\text{C}} = 200 \text{ A}$	8.1		
Total switching energy	E_{ts}	$V_{\text{CC}} = 470 \text{ V}$, $V_{\text{GE}} = -8/15 \text{ V}$, $R_{\text{G(on)}} = 5 \Omega$, $R_{\text{G(off)}} = 5 \Omega$	$T_{\text{vj}} = 25 \text{ }^{\circ}\text{C}$, $I_{\text{C}} = 200 \text{ A}$	22.3		mJ
			$T_{\text{vj}} = 175 \text{ }^{\circ}\text{C}$, $I_{\text{C}} = 200 \text{ A}$	24.4		
Operating junction temperature	T_{vj}		-40		175	$^{\circ}\text{C}$

1) includes reverse recovery losses

3 Diode

Table 4 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Diode forward current, limited by T_{vjmax}	I_{F}		$T_{\text{c}} = 25 \text{ }^{\circ}\text{C}$	250	A
			$T_{\text{c}} = 100 \text{ }^{\circ}\text{C}$	200	
Diode pulsed current, t_{p} limited by T_{vjmax}	I_{Fpulse}			600	A
Power dissipation	P_{tot}	$T_{\text{vj}} = 175 \text{ }^{\circ}\text{C}$	$T_{\text{c}} = 25 \text{ }^{\circ}\text{C}$	500	W
			$T_{\text{c}} = 100 \text{ }^{\circ}\text{C}$	250	

Table 5 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode forward voltage	V_{F}	$I_{\text{F}} = 200 \text{ A}$	$T_{\text{vj}} = 25 \text{ }^{\circ}\text{C}$		1.9	2	V
			$T_{\text{vj}} = 175 \text{ }^{\circ}\text{C}$		1.9		
Diode reverse recovery charge	Q_{rr}	$V_{\text{R}} = 470 \text{ V}$	$T_{\text{vj}} = 25 \text{ }^{\circ}\text{C}$, $I_{\text{F}} = 200 \text{ A}$, $-di_{\text{F}}/dt = 1060 \text{ A}/\mu\text{s}$		4.7		μC
			$T_{\text{vj}} = 175 \text{ }^{\circ}\text{C}$, $I_{\text{F}} = 200 \text{ A}$, $-di_{\text{F}}/dt = 1110 \text{ A}/\mu\text{s}$		7.5		

(table continues...)

Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode peak reverse recovery current	I_{rrm}	$V_R = 470 \text{ V}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1060 \text{ A}/\mu\text{s}$		41		A
			$T_{vj} = 175 \text{ }^{\circ}\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1110 \text{ A}/\mu\text{s}$		56		
Reverse recovery energy	E_{rec}	$V_R = 470 \text{ V}$, $L_{\sigma} = 50 \text{ nH}$, $C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1060 \text{ A}/\mu\text{s}$		1.3		mJ
			$T_{vj} = 175 \text{ }^{\circ}\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1110 \text{ A}/\mu\text{s}$		2.2		
Operating junction temperature	T_{vj}			-40		175	$^{\circ}\text{C}$

Note: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Electrical Characteristic at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified.

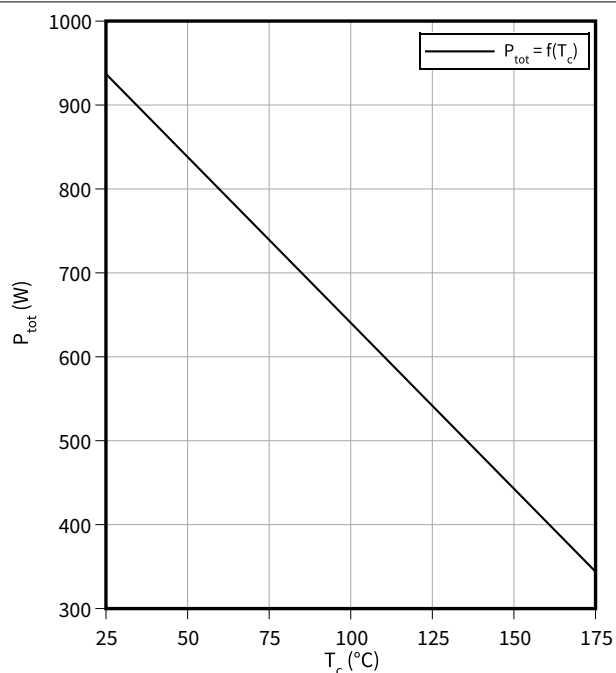
Dynamic test circuit, parasitic inductance $L_{\sigma} = 50 \text{ nH}$, parasitic capacitor $C_{\sigma} = 30 \text{ pF}$ from Fig. E. Energy losses include "tail" and diode reverse recovery.

4 Characteristics diagrams

Power dissipation as a function of case temperature

$$P_{\text{tot}} = f(T_c)$$

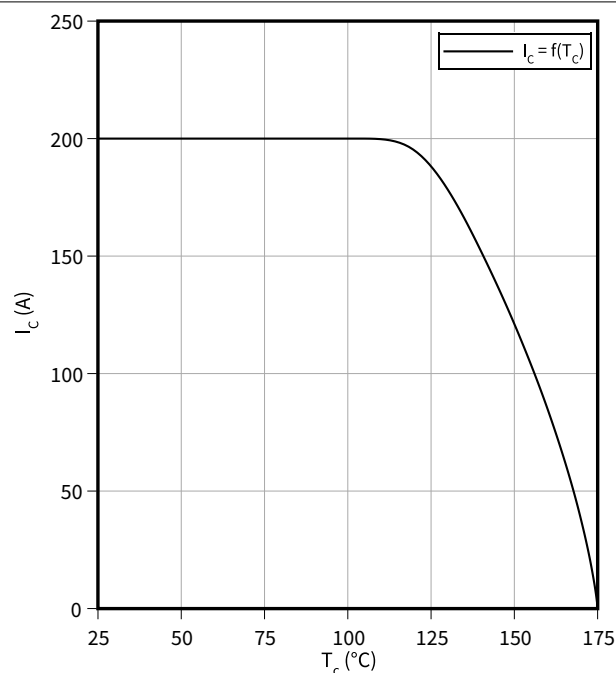
$$T_{vj} \leq 175\text{ °C}$$



Collector current as a function of case temperature

$$I_c = f(T_c)$$

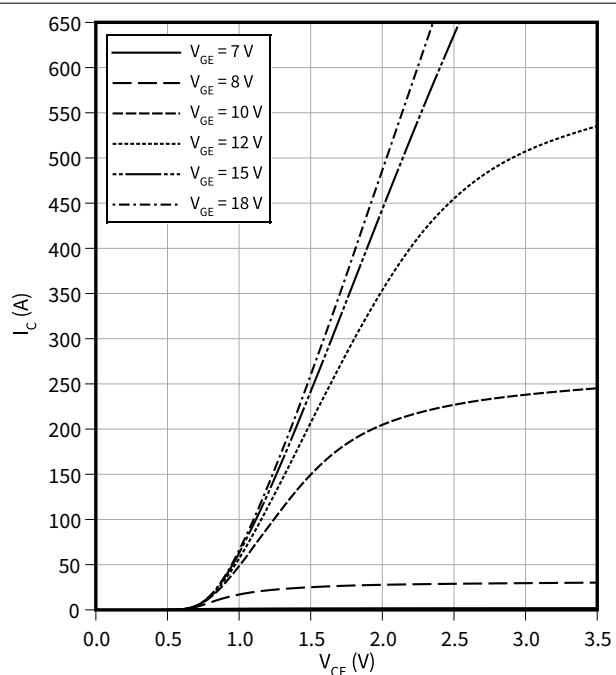
$$T_{vj} \leq 175\text{ °C}, V_{GE} = 15\text{ V}$$



Typical output characteristic

$$I_c = f(V_{CE})$$

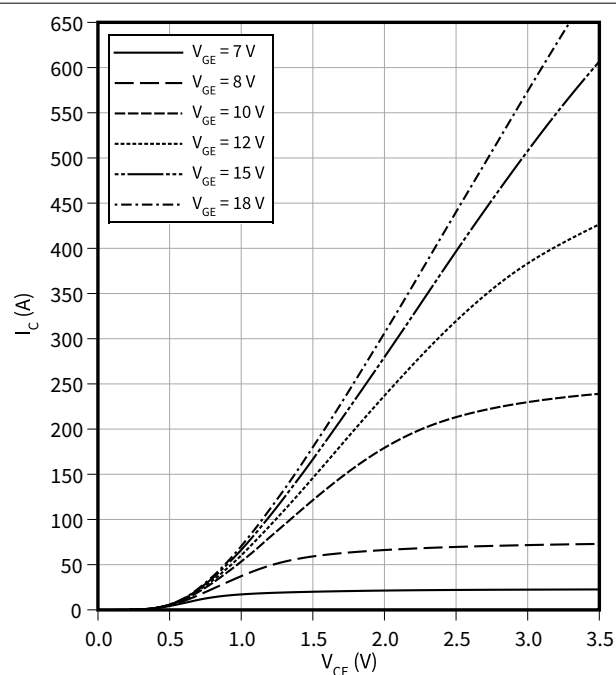
$$T_{vj} = 25\text{ °C}$$



Typical output characteristic

$$I_c = f(V_{CE})$$

$$T_{vj} = 175\text{ °C}$$

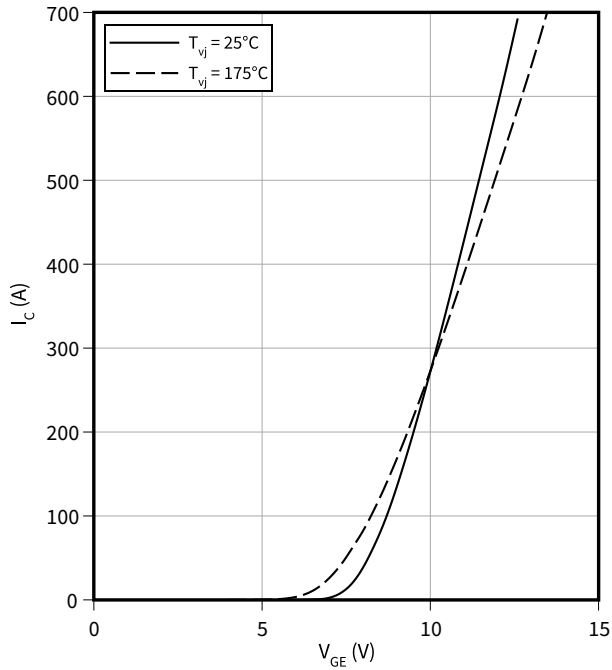


4 Characteristics diagrams

Typical transfer characteristic

$$I_C = f(V_{GE})$$

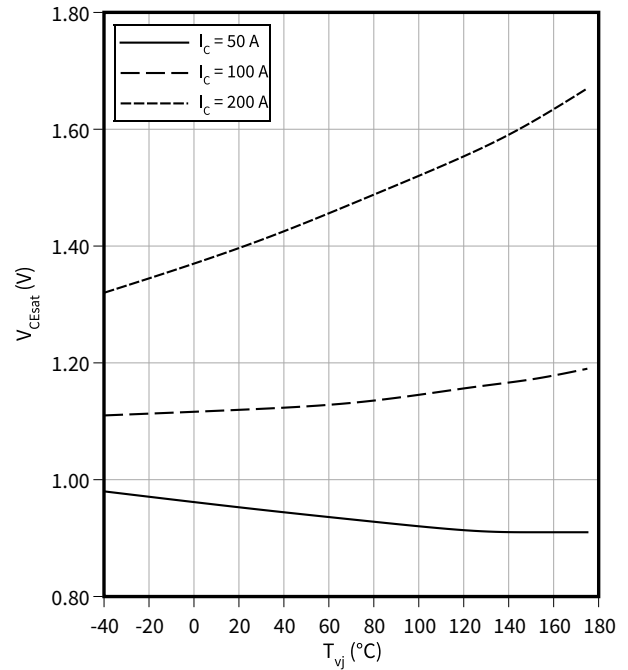
$$V_{CE} = 20 \text{ V}$$



Typical collector-emitter saturation voltage as a function of junction temperature

$$V_{CEsat} = f(T_{vj})$$

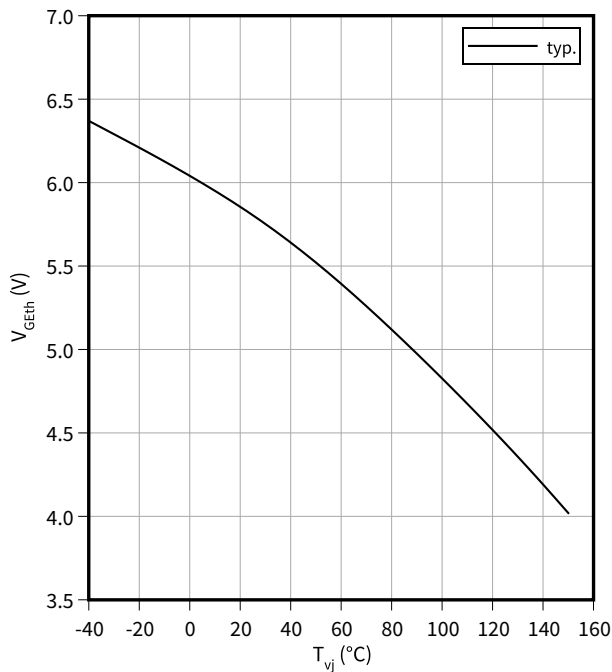
$$V_{GE} = 15 \text{ V}$$



Gate-emitter threshold voltage as a function of junction temperature

$$V_{GEth} = f(T_{vj})$$

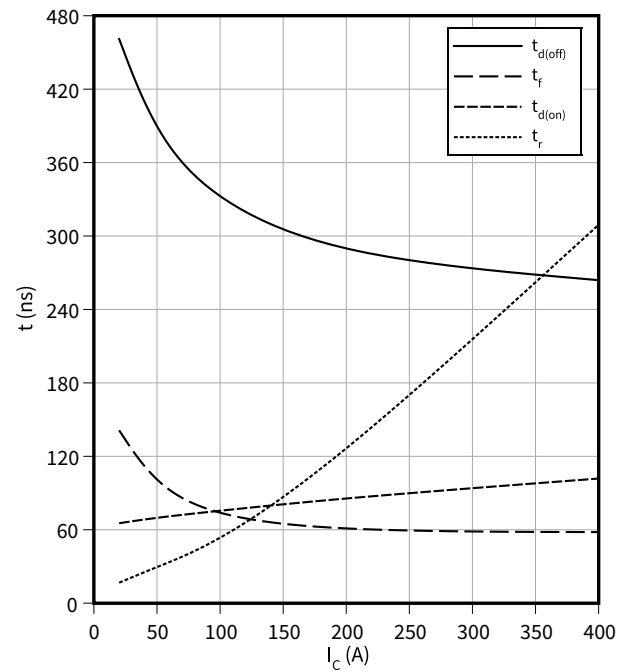
$$I_C = 2.6 \text{ mA}$$



Typical switching times as a function of collector current

$$t = f(I_C)$$

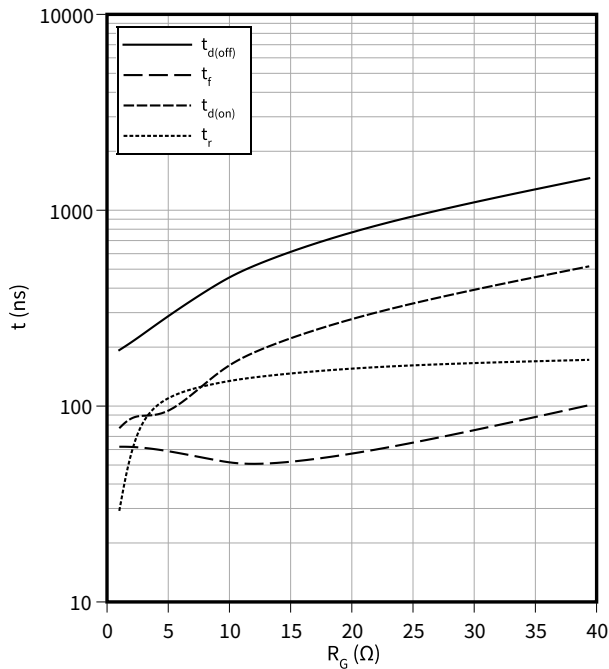
$$V_{CC} = 470 \text{ V}, T_{vj} = 175^\circ\text{C}, V_{GE} = -8/15 \text{ V}, R_G = 5 \Omega$$



4 Characteristics diagrams

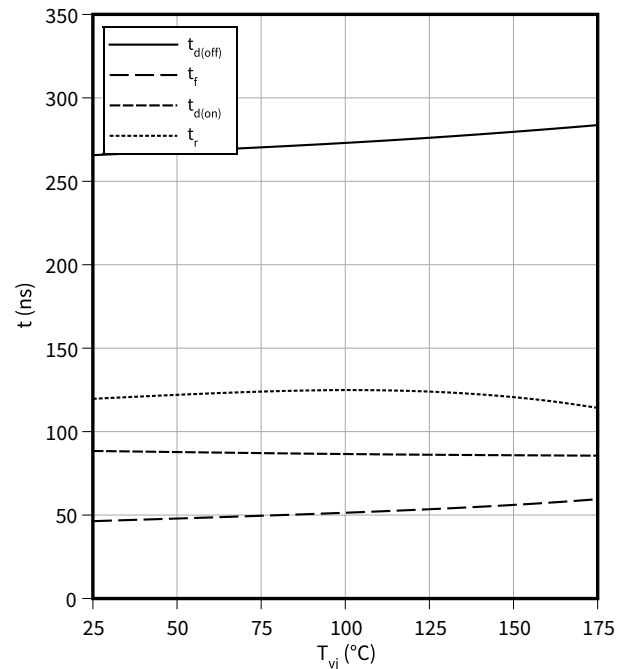
Typical switching times as a function of gate resistor

$$t = f(R_G)$$

 $I_C = 200 \text{ A}, V_{CC} = 470 \text{ V}, T_{vj} = 175 \text{ }^\circ\text{C}, V_{GE} = -8/15 \text{ V}$


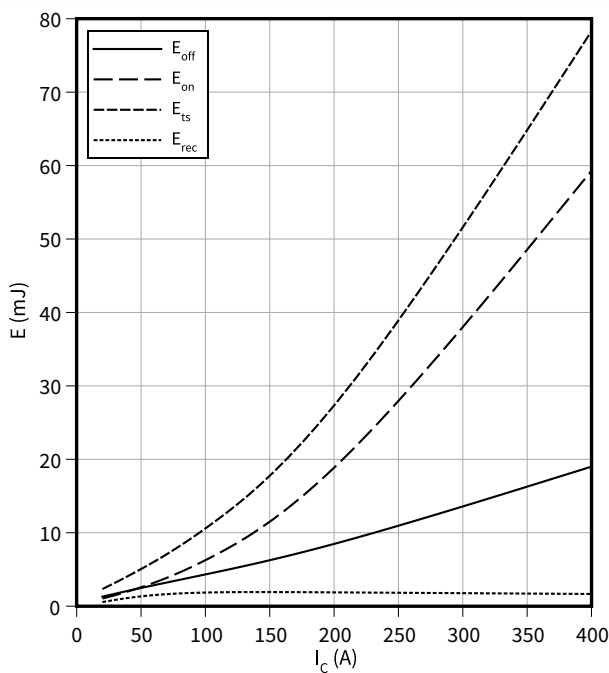
Typical switching times as a function of junction temperature

$$t = f(T_{vj})$$

 $I_C = 200 \text{ A}, V_{CC} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_G = 5 \text{ } \Omega$


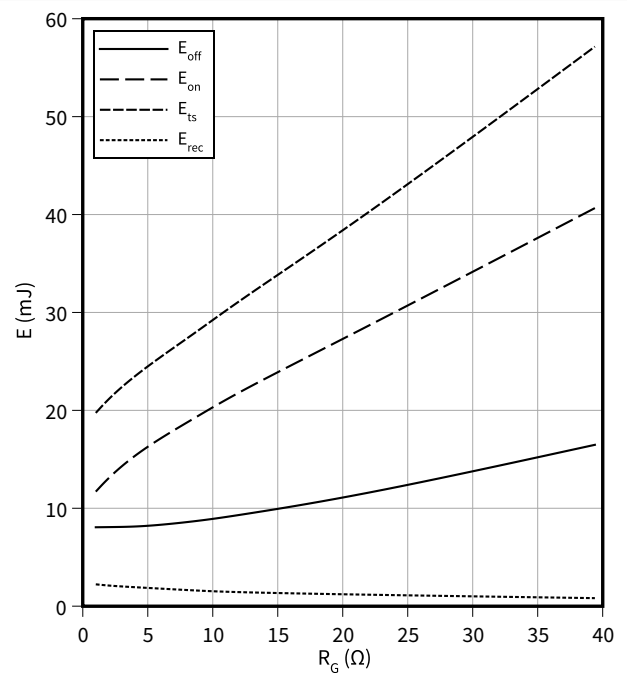
Typical switching energy losses as a function of collector current

$$E = f(I_C)$$

 $V_{CC} = 470 \text{ V}, T_{vj} = 175 \text{ }^\circ\text{C}, V_{GE} = -8/15 \text{ V}, R_G = 5 \text{ } \Omega$


Typical switching energy losses as a function of gate resistor

$$E = f(R_G)$$

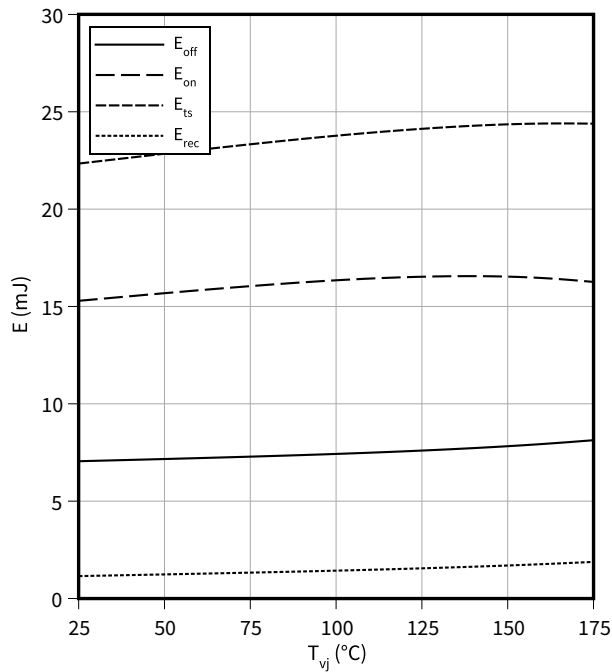
 $I_C = 200 \text{ A}, V_{CC} = 470 \text{ V}, T_{vj} = 175 \text{ }^\circ\text{C}, V_{GE} = -8/15 \text{ V}$


4 Characteristics diagrams

Typical switching energy losses as a function of junction temperature

$$E = f(T_{vj})$$

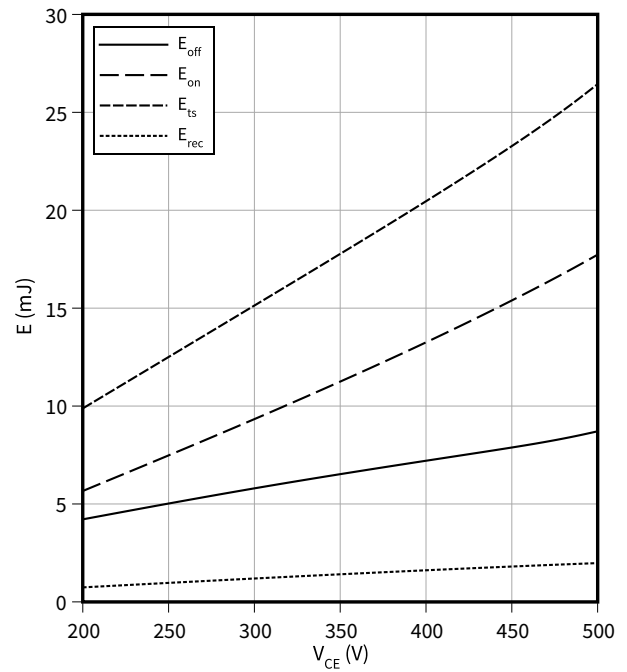
$I_C = 200 \text{ A}$, $V_{CC} = 470 \text{ V}$, $V_{GE} = -8/15 \text{ V}$, $R_G = 5 \Omega$



Typical switching energy losses as a function of collector emitter voltage

$$E = f(V_{CE})$$

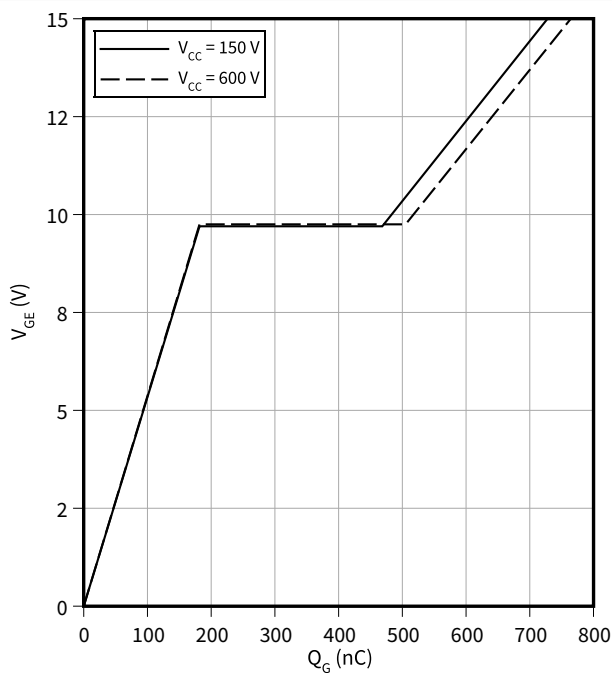
$I_C = 200 \text{ A}$, $V_{GE} = -8/15 \text{ V}$, $T_{vj} = 175 \text{ °C}$, $R_G = 5 \Omega$



Typical gate charge

$$V_{GE} = f(Q_G)$$

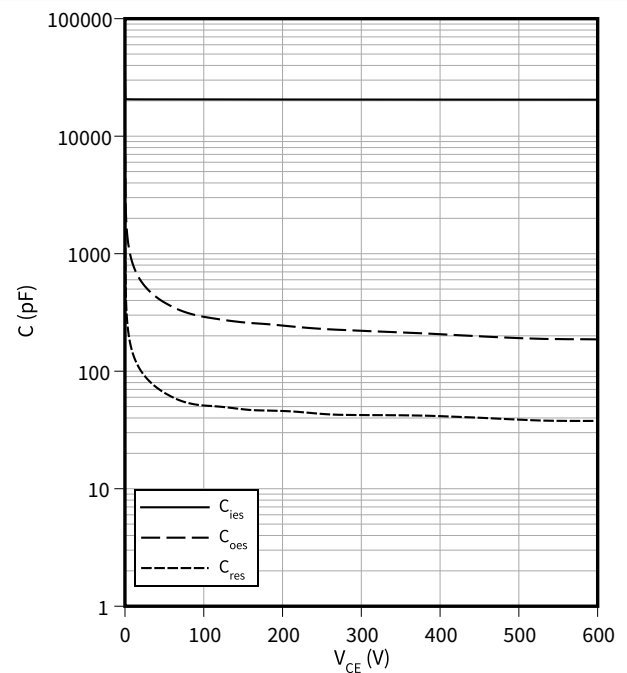
$I_C = 200 \text{ A}$



Typical capacitance as a function of collector-emitter voltage

$$C = f(V_{CE})$$

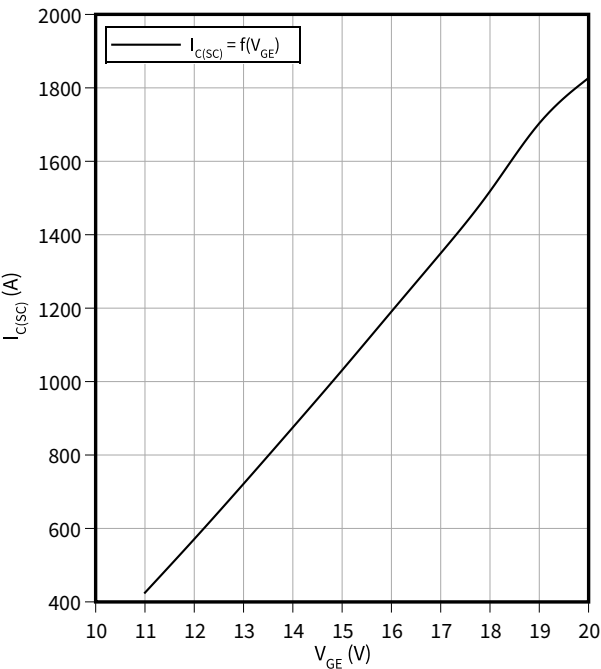
$f = 100 \text{ kHz}$, $V_{GE} = 0 \text{ V}$



4 Characteristics diagrams

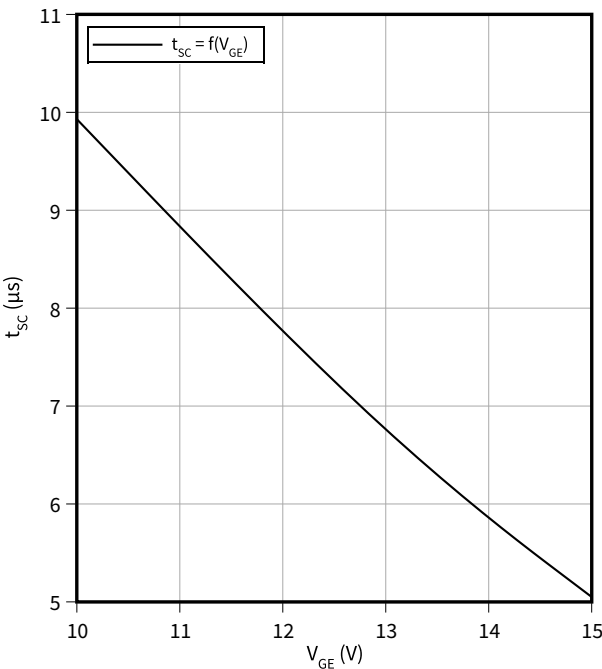
Typical short circuit collector current as a function of gate-emitter voltage

$I_{C(SC)} = f(V_{GE})$
 $T_{vj} \leq 175\text{ }^{\circ}\text{C}, V_{CC} \leq 470\text{ V}$



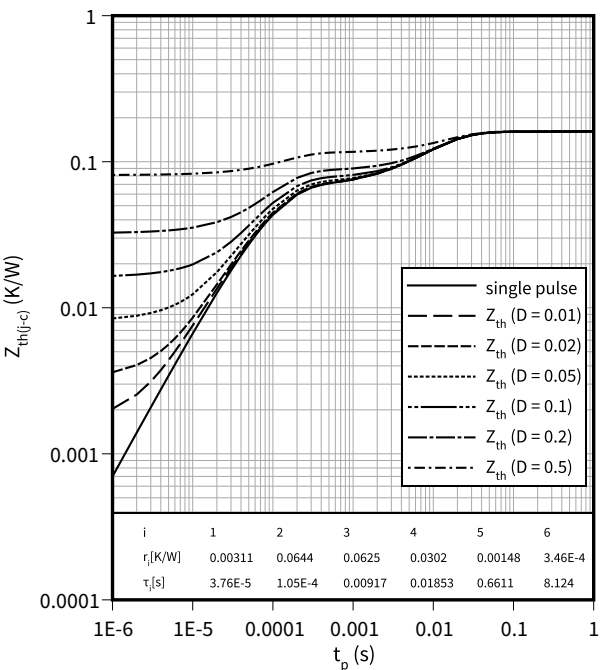
Short circuit withstand time as a function of gate-emitter voltage

$t_{SC} = f(V_{GE})$
 $T_{vj} \leq 175\text{ }^{\circ}\text{C}, V_{CC} \leq 470\text{ V}$



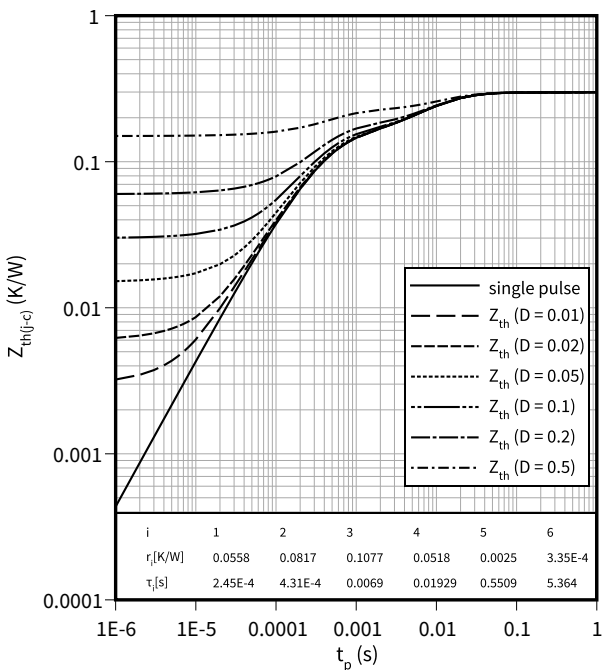
IGBT transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$
 $D = t_p/T$

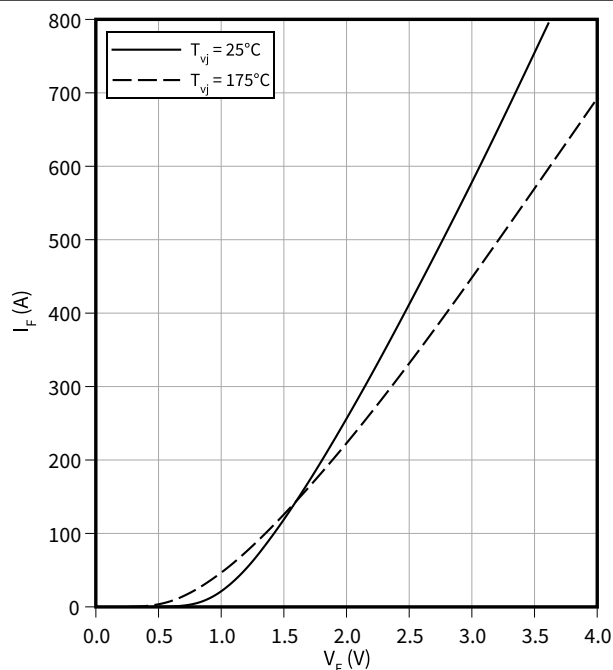
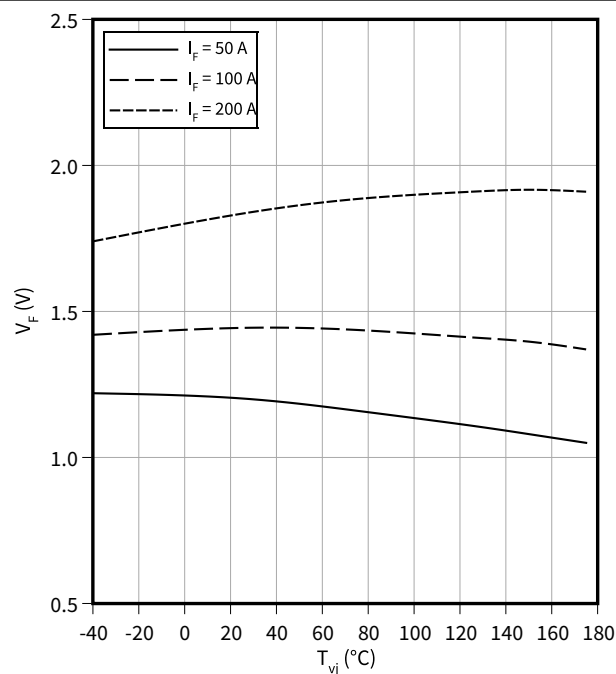
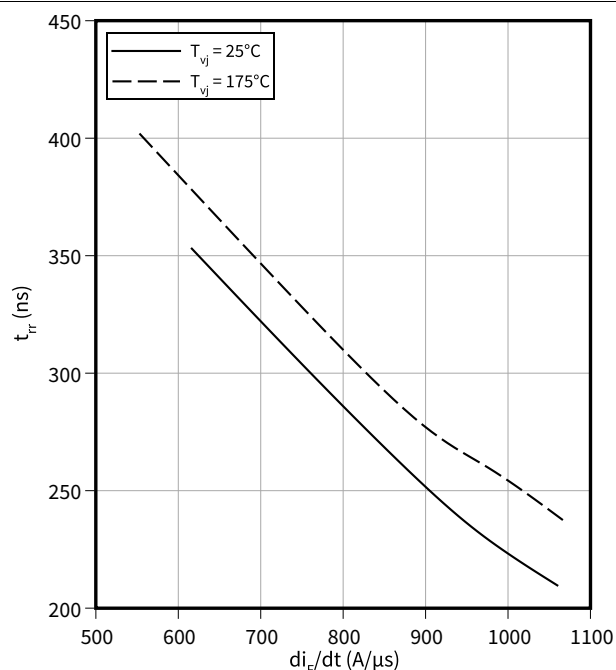
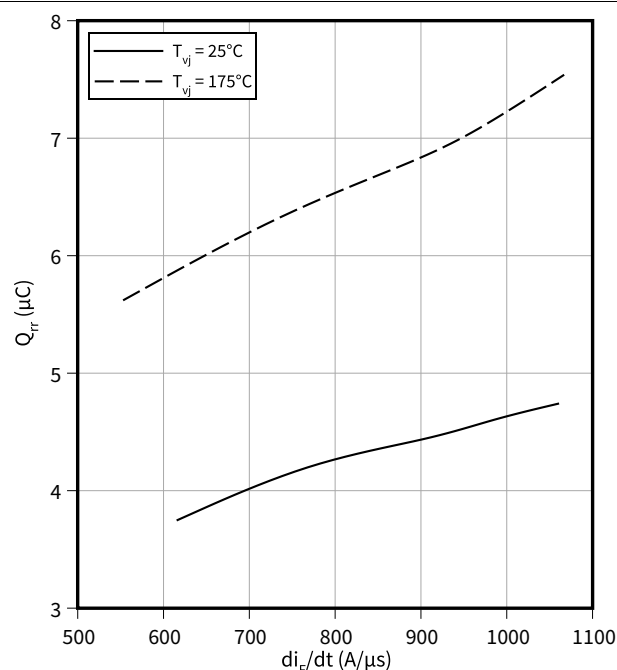


Diode transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$
 $D = t_p/T$



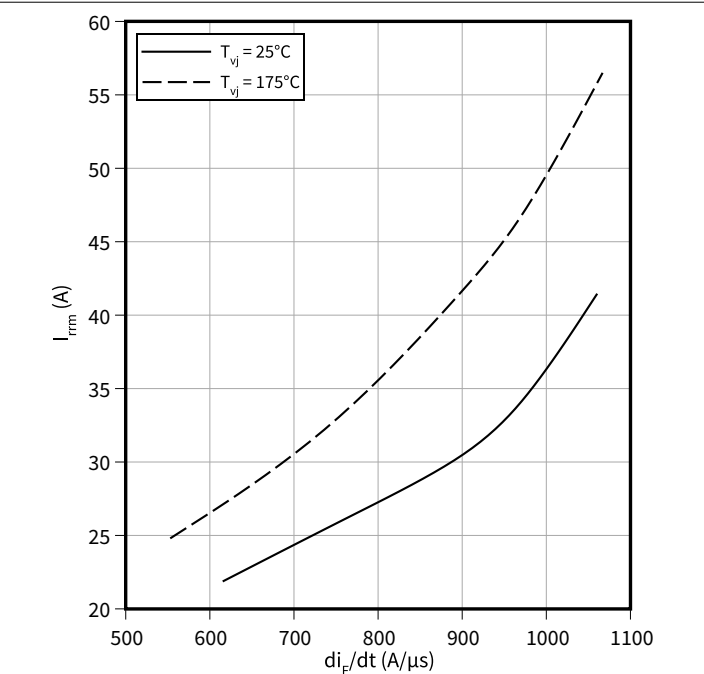
4 Characteristics diagrams

Typical diode forward current as a function of forward voltage
 $I_F = f(V_F)$

Typical diode forward voltage as a function of junction temperature
 $V_F = f(T_{vj})$

Typical reverse recovery time as a function of diode current slope
 $t_{rr} = f(di_F/dt)$
 $V_R = 470\text{ V}, I_F = 200\text{ A}$

Typical reverse recovery charge as a function of diode current slope
 $Q_{rr} = f(di_F/dt)$
 $V_R = 470\text{ V}, I_F = 200\text{ A}$


4 Characteristics diagrams

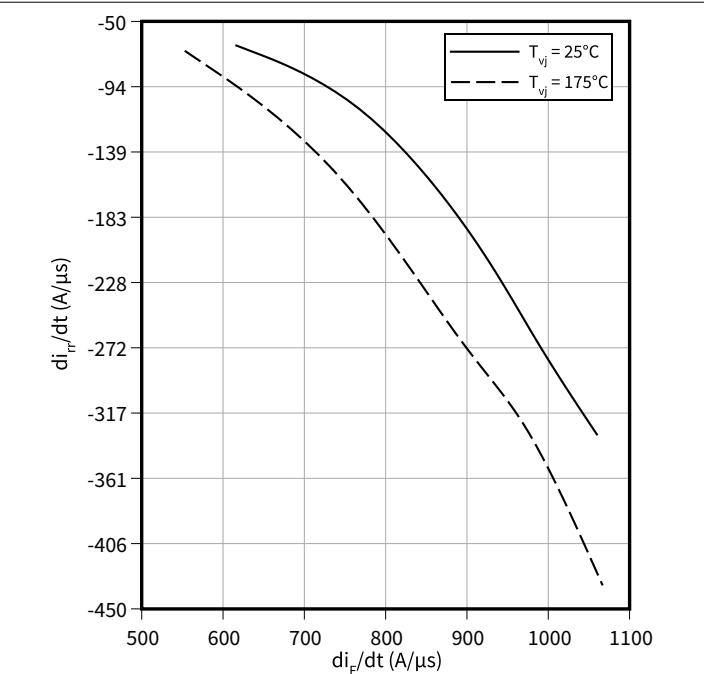
Typical reverse recovery current as a function of diode current slope

$I_{rrm} = f(di_F/dt)$
 $V_R = 470\text{ V}, I_F = 200\text{ A}$



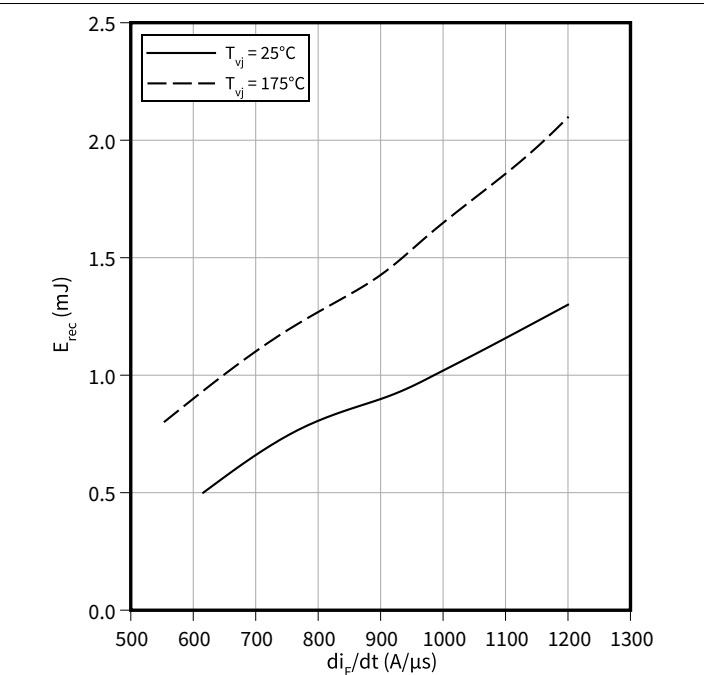
Typical diode peak rate of fall of reverse recovery current as a function of diode current slope

$di_{rr}/dt = f(di_F/dt)$
 $V_R = 470\text{ V}, I_F = 200\text{ A}$



Typical reverse energy losses as a function of diode current slope

$E_{rec} = f(di_F/dt)$
 $V_R = V, I_F = 200\text{ A}$



5 Package outlines

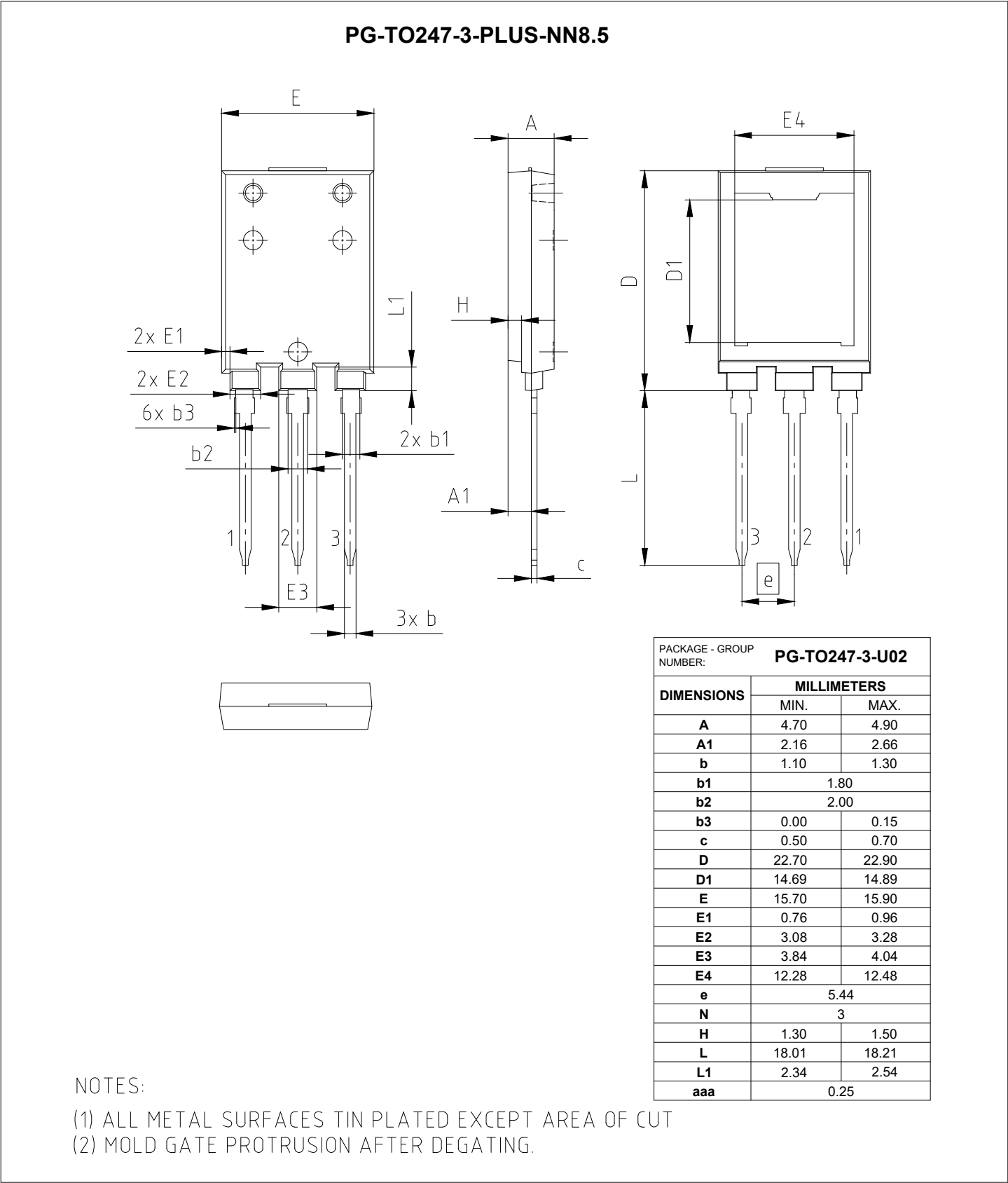


Figure 1

6 Testing conditions

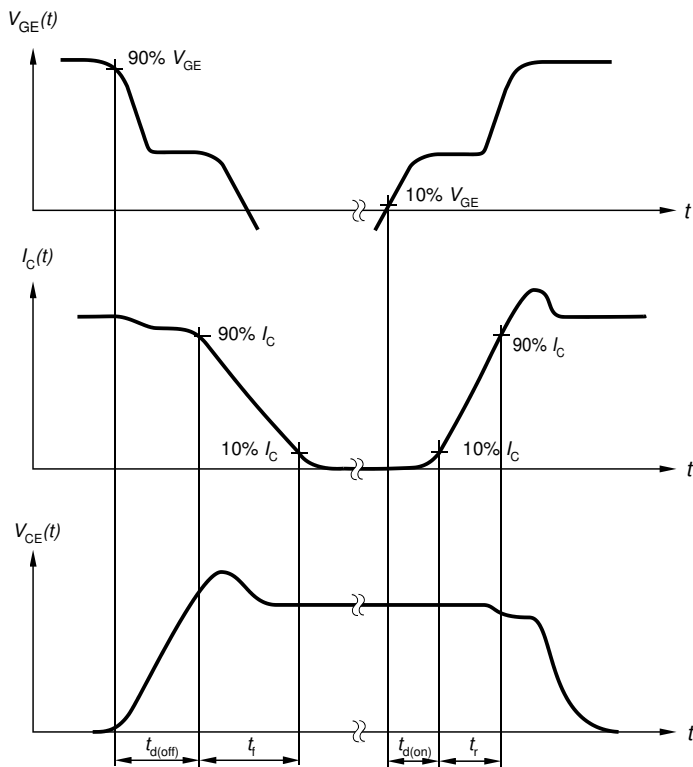


Figure A. Definition of switching times

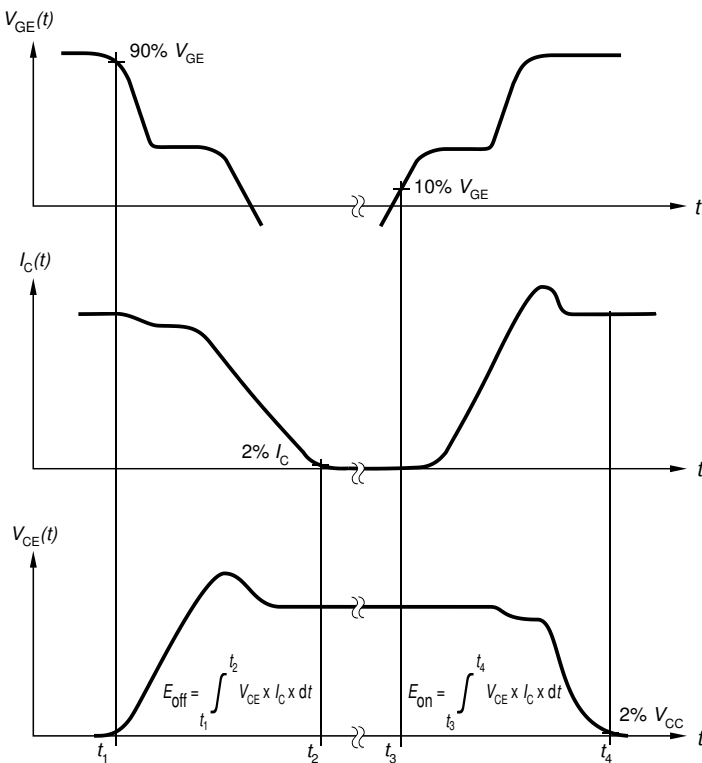


Figure B. Definition of switching losses

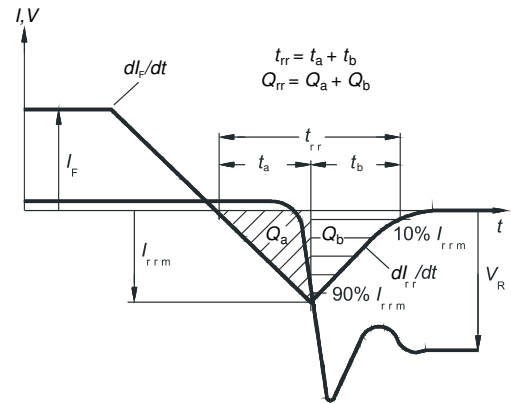


Figure C. Definition of diode switching characteristics

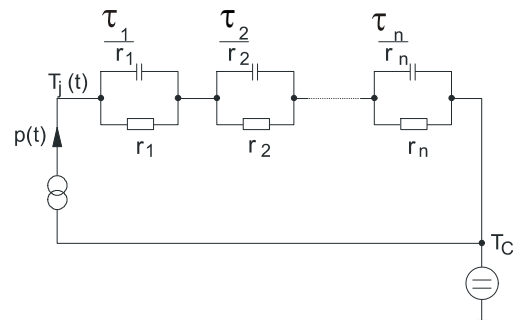


Figure D. Thermal equivalent circuit

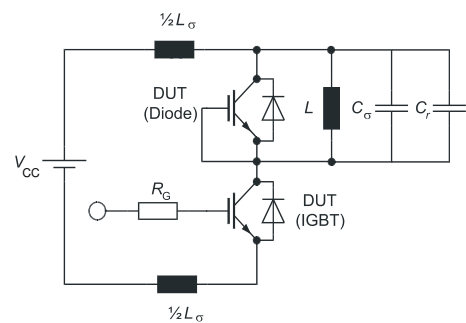


Figure E. **Dynamic test circuit**
 Parasitic inductance L_{σ} ,
 parasitic capacitor C_{σ} ,
 relief capacitor C_r ,
 (only for ZVT switching)

Revision history

Document revision	Date of release	Description of changes
0.10	2023-02-21	Target datasheet
0.20	2024-02-21	Preliminary datasheet

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